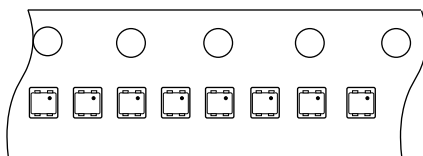
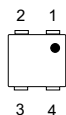
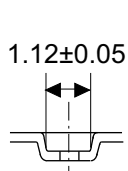
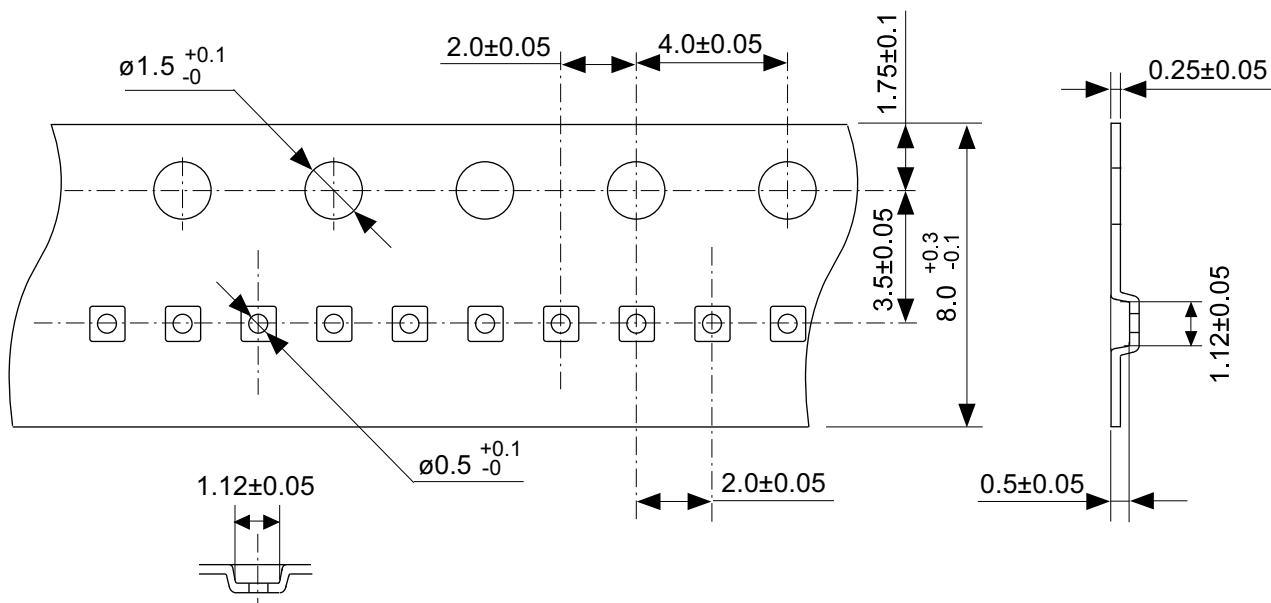


※ The heat sink of back side has different electric potential depending on the product.
 Confirm specifications of each product.
 Do not use it as the function of electrode.

No. PL004-A-P-SD-1.1

TITLE	HSNT-4-B-PKG Dimensions
No.	PL004-A-P-SD-1.1
ANGLE	
UNIT	mm
ABLIC Inc.	

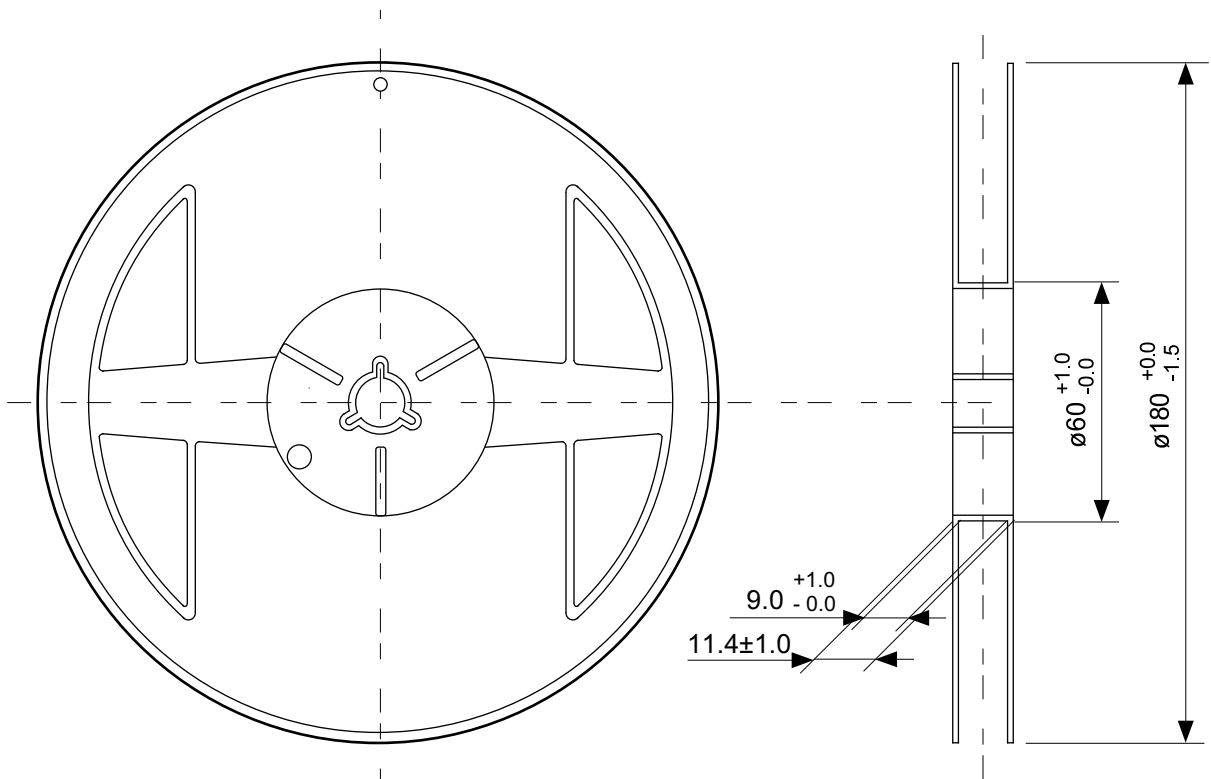


→
Feed direction

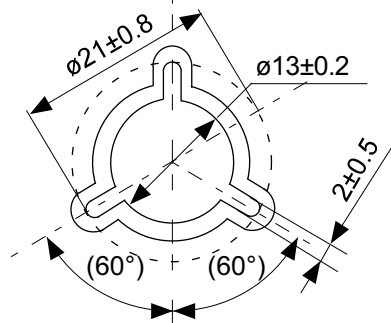
No. PL004-A-C-SD-2.0

TITLE	HSNT-4-B-Carrier Tape
No.	PL004-A-C-SD-2.0
ANGLE	
UNIT	mm
ABLIC Inc.	

The information herein is subject to change without notice.



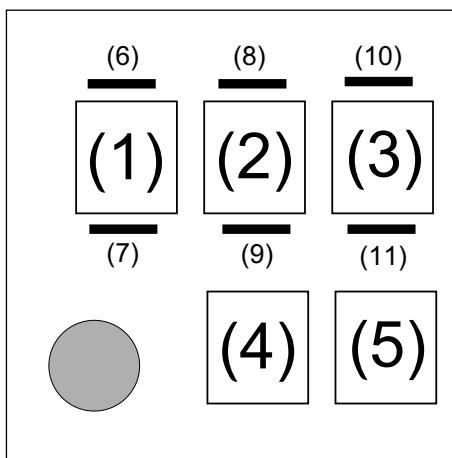
Enlarged drawing in the central part



No. PL004-A-R-SD-1.0

TITLE	HSNT-4-B-Reel		
No.	PL004-A-R-SD-1.0		
ANGLE		QTY.	10,000
UNIT	mm		
ABLIC Inc.			

The information herein is subject to change without notice.



PKG PIN#1

(1) to (3) : Product code

(4), (5) : Lot No.

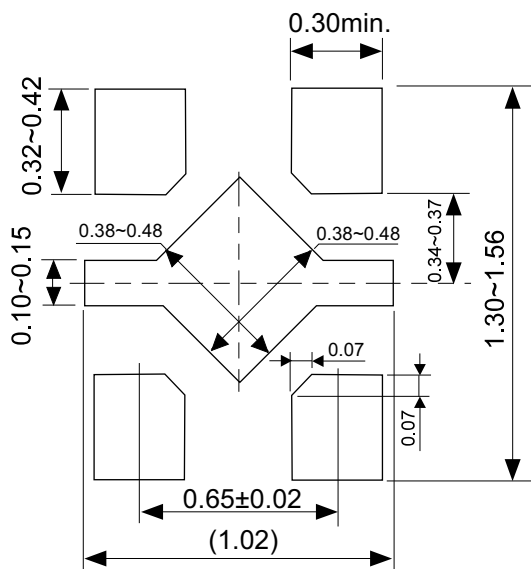
(6), (7) : Year of assembly (bar)

(8) to (11): Month of assembly (bar)

No. PL004-A-M-SD-1.0

TITLE	HSNT-4-B-Markings		
No.	PL004-A-M-SD-1.0		
ANGLE			
UNIT		TYPE	LASER
ABLIC Inc.			

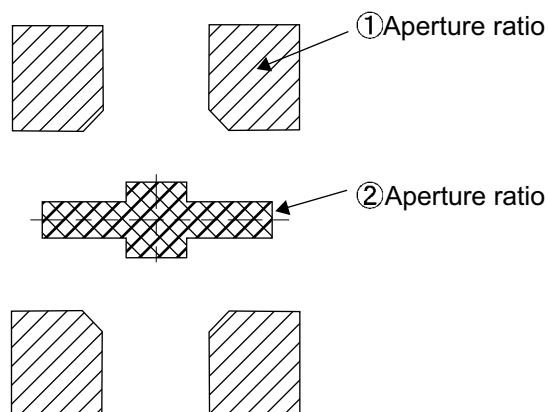
Land Pattern



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

Metal Mask Pattern



Caution ① Mask aperture ratio of the lead mounting part is 100%.
 ② Mask aperture ratio of the heat sink mounting part is 40%.
 ③ Mask thickness: t:0.10mm to 0.12 mm

注意 ①リード実装部のマスク開口率は100%です。
 ②放熱板実装のマスク開口率は40%です。
 ③マスク厚み : t:0.10mm ~ 0.12 mm

No. PL004-A-L-SD-2.0

TITLE	HSNT-4-B -Land Recommendation
No.	PL004-A-L-SD-2.0
ANGLE	
UNIT	mm
ABLIC Inc.	